

This application also contains subject matter related to U.S. application Ser. No. 09/470, 651, which is a continuation of pending U.S. application Ser. No. 09/046,835 mentioned above. --

IN THE CLAIMS

Please cancel claims 1-19 and 23-43 without prejudice.

Please amend the following claim.

~~20. (Once amended) [The method in claim 19] A method of providing a polymer between metal lines on a wafer, comprising:~~

~~providing a plasma source, wherein said step of providing a plasma source [further] comprises providing a plasma source chamber; exposing said wafer to said plasma source, wherein said step of [and] exposing said wafer to said plasma source further comprises placing said wafer in said plasma source chamber;~~  
~~introducing a feed gas to said wafer;~~  
~~establishing a pressure around said wafer; and~~  
~~forming said polymer between said metal lines using said feed gas.~~

Remarks

Claims 1-46 were pending up to this Amendment.

Claims 1-46 were rejected.

Claims 1-19 and 23-43 are cancelled.

Claim 20 is amended.

Claims 20-22 and 44-46 are pending as of this Amendment.

The Examiner rejected claims 1-46 on various bases. Applicants will present arguments in support of claims 1-19 and 23-43 in a related application. Accordingly,